

ICSICT 2018

International Conference on Solid-State and Integrated Circuit Technology

Oct.31-Nov.3, 2018

Huangdao Sheraton Hotel,
Qingdao, China

<http://www.icsict.com>

FIRST CALL FOR PAPERS

The ICSICT-2018 conference is the 14th in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct.31-Nov.3, 2018 in Qingdao, China. All aspects of solid-state devices, circuits, processing technologies, materials and other related research are within the scope of the conference. The three days of contributed and invited presentations on the latest developments in diverse fields given in oral and poster sessions, panel discussions on leading edge technology issues, and other activities will provide extensive opportunities for technical information exchange as well as a stimulating environment for mutual communication among participants. Excellent Student Paper Award will be presented at the closing of the conference.

THE SCOPE AND TOPICS OF THE CONFERENCE

(Papers are solicited in, but not limited to the following areas)

VLSI Technologies

1. Channel Engineering
2. High-k/Metal gate Technology
3. Advanced Source/Drain Technology
4. Interconnect Technology
5. Advanced 3D Integration
6. Novel Process Technologies
7. Ultra-Thin Body Transistors
8. High Performance CMOS Platforms
9. CMOS Like Novel Devices
10. Advanced FinFETs and Nanowire FETs
11. CNT, MTJ Devices and Nanowire Devices
12. Low- Power and Steep Slope Switching Devices
13. 2D Devices & Technologies
14. Advanced Technologies for Ge MOSFETs
15. Organic semiconductor devices and technologies
16. Compound semiconductor devices and Technology
17. Ultra High Speed Transistors, HEMT/HBT etc.
18. Photoelectron Devices
19. Advanced Power Devices and Reliability
20. Flash Memory
21. IT Magnetic RAM

22. Resistive RAMs
23. Phase Change Memory
24. 3-Dimensional Memory
25. MEMS Technology
26. Thin Film Transistors
27. Sensors
28. PV and Energy Harvesting
29. Front End of Line (FEOL) Reliability
30. Memory Reliability
31. Back-End of Line and ESD Reliability
32. Device Simulation & Modeling
33. Process Simulation & Modeling
34. Artificial Intelligence (Process & Device)
35. Internet of Things (Process & Device)

VLSI Circuits & ICCAD

36. Processors
37. Analog Circuits
38. SOC
39. PLL and CDR
40. Low-Power Nyquist ADCs
41. Digital Circuits Resilient
42. High-Resolution and High Speed Data Converters
43. Digital Chip-to-Chip and On-Die Interfaces
44. Advanced Clock
45. Artificial Intelligence (Circuits & System)
46. Internet of Things (Circuits & System)
47. FPGA
48. Memory Circuits
49. Advanced Transceivers Techniques
50. EDA
51. RF Circuits and Systems
52. Interference Robust RF Receivers
53. Signal Processing
54. System-Level Modeling & Simulation/Verification
55. System-Level Synthesis & Optimization
56. High-Level/Behavioral/Logic Synthesis & Optimization
57. Physical Design
58. DFM

PAPER SUBMISSION

Prospective authors are requested to submit **3 pages** camera-ready full length paper in English for proceedings publication. The proceedings will have an IEEE catalogue number and will be collected in IEEE publication database --- IEEE X[®] *plere*.

Deadline for Camera-Ready Full-Length

Paper Submission: June 30, 2018.

Notification of Acceptance: Aug. 15, 2018

On-line submission at web-site <http://www.icsict.com> is required.

About paper submission, please contact:

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